

Omar El-Aassar

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	Octave-Tuning Dual-Core Folded VCO Leveraging a Triple-Mode Switch-Less Tertiary Magnetic Loop. IEEE Journal of Solid-State Circuits, 2021, 56, 1475-1486.	5.4	21
2	A Dual-Core 8-17 GHz LC VCO with Enhanced Tuning Switch-less Tertiary Winding and 208.8 dBc/Hz Peak FoM_T in 22nm FDSOI. , 2020, , .		10
3	A 16 Path All-Passive Harmonic Rejection Mixer With Watt-Level In-Band IIP3 in 45-nm CMOS SOI. IEEE Microwave and Wireless Components Letters, 2020, 30, 790-793.	3.2	4
4	Design of Low-Power Sub-2.4 dB Mean NF 5G LNAs Using Forward Body Bias in 22 nm FDSOI. IEEE Transactions on Microwave Theory and Techniques, 2020, 68, 4445-4454.	4.6	25
5	A 5 GHz 0.5 V Hybrid Class-B/F₁ CMOS Oscillator With ~ 147 dBc/Hz Phase Noise at 10 MHz Offset Using Body-Biased 22 nm FDSOI. IEEE Microwave and Wireless Components Letters, 2020, 30, 973-976.	3.2	2
6	A Cascaded Multi-Drive Stacked-SOI Distributed Power Amplifier With 23.5 dBm Peak Output Power and Over 4.5-THz GBW. IEEE Transactions on Microwave Theory and Techniques, 2020, 68, 3111-3119.	4.6	18
7	A Stacked-Complementary 5 GHz Oscillator With Even-Only Differential Harmonic Shaping Achieving ~ 150 dBc/Hz Phase Noise at 10-MHz Offset Using Body-Biased Thin-Oxide 22-nm FDSOI. IEEE Solid-State Circuits Letters, 2020, 3, 98-101.	2.0	3
8	A 120-GHz Bandwidth CMOS Distributed Power Amplifier With Multi-Drive Intra-Stack Coupling. IEEE Microwave and Wireless Components Letters, 2020, 30, 782-785.	3.2	15
9	A Compact pMOS Stacked-SOI Distributed Power Amplifier With Over 100-GHz Bandwidth and Up to 22-dBm Saturated Output Power. IEEE Solid-State Circuits Letters, 2019, 2, 9-12.	2.0	17
10	A DC-to-108-GHz CMOS SOI Distributed Power Amplifier and Modulator Driver Leveraging Multi-Drive Complementary Stacked Cells. IEEE Journal of Solid-State Circuits, 2019, 54, 3437-3451.	5.4	37
11	4.7 A Compact DC-to-108GHz Stacked-SOI Distributed PA/Driver Using Multi-Drive Inter-Stack Coupling, Achieving 1.525THz GBW, 20.8dBm Peak P_{1dB}, and Over 100Gb/s in 64-QAM and PAM-4 Modulation. , 2019, , .		11
12	Loss Mechanisms and Optimum Design Methodology for Efficient mm-Waves Class-E PAs. IEEE Transactions on Circuits and Systems I: Regular Papers, 2016, 63, 773-784.	5.4	2